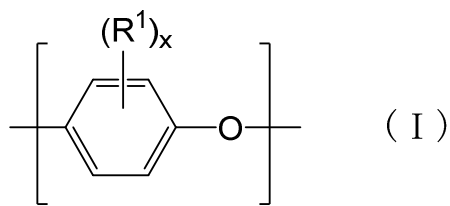


ABSTRACT

Provided are a resin composition having especially good compatibility and having dielectric properties (low dielectric constant and low dielectric dissipation factor) in a high frequency range, high adhesion to conductor, excellent heat resistance, high glass transition temperature, low thermal expansion coefficient and high flame retardancy, and a prepreg, a laminate and a multilayer printed wiring board using the resin composition. Specifically, the resin composition contains (A) a polyphenylene ether derivative having an N-substituted maleimide structure-containing group and a structural unit represented by the following general formula (I) in one molecule, (B) at least one thermosetting resin selected from the group consisting of epoxy resins, cyanate resins and maleimide compounds, and (C) a styrenic thermoplastic elastomer:



wherein R^1 each independently represents an aliphatic hydrocarbon group having 1 to 5 carbon atoms, or a halogen atom, and x represents an integer of 0 to 4.